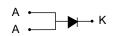
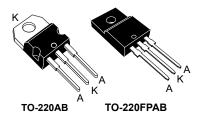




# 100 V, 40 A field-effect rectifier diode







#### **Features**

- · ST patented rectifier process
- · Stable leakage current over reverse voltage
- · Low forward voltage drop
- High frequency operation
- ECOPACK<sup>®</sup>2 compliant

#### **Applications**

- Adapter
- · Gaming console power supply
- · Battery charger
- DC / DC converter

#### **Description**

This single rectifier is based on a proprietary technology, enabling to achieve the best in class  $V_F/I_R$  for a given silicon surface.

Packaged in TO-220AB, TO-220FPAB and D $^2$ PAK, the FERD40H100S is optimized for use in confined applications where both efficiency and thermal performance are key. With a lower dependency of leakage current ( $I_R$ ) and forward voltage ( $V_F$ ) in function of temperature, the thermal runaway risk is reduced. It is highly recommended to be used in adapters and chargers.

Product status
FERD40H100S

Product summary			
Symbol Value			
I <sub>F(AV)</sub>	40 A		
V <sub>RRM</sub>	100 V		
T <sub>j(max.)</sub>	175 °C		
V <sub>F(typ.)</sub>	0.325 V		



#### 1 Characteristics

Table 1. Absolute ratings (limiting values at 25 °C, unless otherwise specified, anode terminals short circuited)

Symbol	Parameter	Value	Unit	
$V_{RRM}$	Repetitive peak reverse voltage	100	V	
I <sub>F(RMS)</sub>	Forward rms current	60	Α	
I <sub>F(AV)</sub>	Average forward current, $\delta$ = 0.5 square wave		40	Α
I <sub>FSM</sub>	Surge non repetitive forward current $t_p = 10 \text{ ms sinusoidal}$		440	Α
T <sub>stg</sub>	Storage temperature range		-65 to +175	°C
T <sub>j</sub>	Maximum operating junction temperature <sup>(1)</sup> +175			°C

<sup>1.</sup>  $(dP_{tot}/dT_j) < (1/R_{th(j-a)})$  condition to avoid thermal runaway for a diode on its own heatsink.

Table 2. Thermal resistance parameter

Symbol	Parameter	Max. value	Unit	
D., ., .	lunation to acco	TO-220AB, D <sup>2</sup> PAK	0.8	°C/W
R <sub>th(j-c)</sub>	Junction to case	TO-220FPAB	3.3	C/VV

Table 3. Static electrical characteristics (anode terminals short circuited)

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
	I <sub>R</sub> <sup>(1)</sup> Reverse leakage current	T <sub>j</sub> = 25 °C	\/_ = \/	-		190	μA
I <sub>R</sub> <sup>(1)</sup>		T <sub>j</sub> = 125 °C	$V_R = V_{RRM}$	-	12	24	Λ
		T <sub>j</sub> = 125 °C	V <sub>R</sub> = 70 V	-	6	12	mA
	V <sub>F</sub> <sup>(2)</sup> Forward voltage drop	T <sub>j</sub> = 25 °C	I <sub>F</sub> = 4 A	-	0.380	0.430	
		T <sub>j</sub> = 125 °C		-	0.325	0.375	
		T <sub>j</sub> = 25 °C	I <sub>F</sub> = 10 A	-	0.465	0.525	
V <sub>F</sub> <sup>(2)</sup>		T <sub>j</sub> = 125 °C		-	0.455	0.510	V
		T <sub>j</sub> = 25 °C	L = 20 A	-	0.600	0.675	
		T <sub>j</sub> = 125 °C	I <sub>F</sub> = 20 A	-	0.550	0.600	
		T <sub>j</sub> = 125 °C	I <sub>F</sub> = 40 A	-	0.645	0.705	

<sup>1.</sup> Pulse test:  $t_p$  = 5 ms,  $\delta$  < 2%

To evaluate the conduction losses, use the following equation:

 $P = 0.420 \text{ x } I_{F(AV)} + 0.009 \text{ x } I_{F}^{2}_{(RMS)}$ 

For more information, please refer to the following application notes related to the power losses :

- AN604: Calculation of conduction losses in a power rectifier
- AN4021: Calculation of reverse losses on a power diode

DS11576 - Rev 2 page 2/14

<sup>2.</sup> Pulse test:  $t_p$  = 380  $\mu$ s,  $\delta$  < 2%



#### 1.1 **Characteristics (curves)**

Figure 1. Average forward current versus case temperature ( $\delta = 0.5$ ) I<sub>F(AV)</sub>(A) 50 40 30 20 T<sub>c</sub>(°C) 0 0 50 75 100 125 150 175

Figure 2. Relative variation of thermal impedance junction to case versus pulse duration (TO-220AB, D<sup>2</sup>PAK)  $Z_{th(j-c)}/R_{th(j-c)}$ 0.9 0.8 0.7 0.6 0.5 0.4 0.3 0.1  $t_p(s)$ 0.0

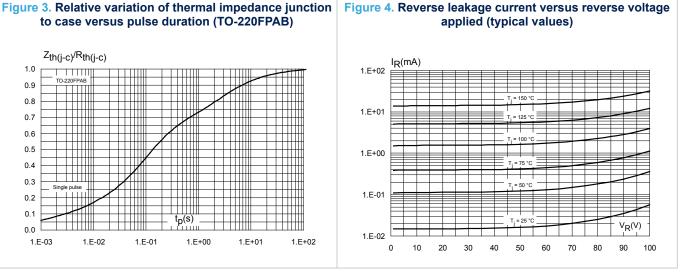
1.E-02

1.E-01

1.E-03

1.E-04

to case versus pulse duration (TO-220FPAB)  $Z_{th(j-c)}/R_{th(j-c)}$ 1.0 ТППП 0.9 0.8 0.7 0.6 0.5 0.4 0.3 0.2 0.1 1.E-03 1.E-02 1.E-01 1.E+00 1.E+01 1.E+02



page 3/14



Figure 5. Junction capacitance versus reverse voltage applied (typical values)

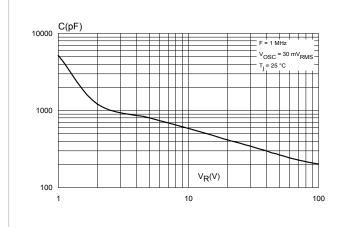


Figure 6. Forward voltage drop versus forward current (typical values)

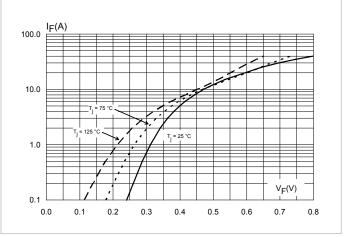


Figure 7. Forward voltage drop versus forward current (typical values)

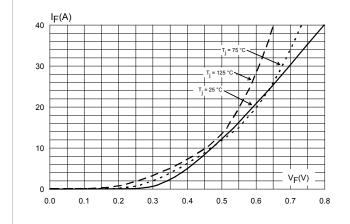
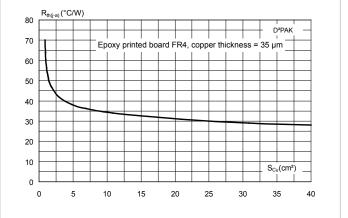


Figure 8. Thermal resistance junction to ambient versus copper surface under tab (typical values)



DS11576 - Rev 2 page 4/14



# Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

#### 2.1 TO-220AB package information

Epoxy meets UL 94,V0

Cooling method: by conduction (C)

Recommended torque value: 0.55 N·m

Maximum torque value: 0.60 N·m

DS11576 - Rev 2 page 5/14



øΡ F Ø H L20 L30 J1 Gate Note 9-10 b (x3)

e1

Figure 9. TO-220AB package outline

DS11576 - Rev 2 page 6/14



Table 4. TO-220AB package mechanical data

	Dimensions					
Ref.	Milli	meters	Inches (for reference only)			
	Min.	Max.	Min.	Max.		
Α	4.40	4.60	0.173	0.181		
b	0.61	0.88	0.024	0.035		
b1	1.14	1.70	0.045	0.067		
С	0.48	0.70	0.019	0.028		
D	15.25	15.75	0.600	0.620		
E	10.00	10.40	0.394	0.409		
е	2.40	2.70	0.094	0.106		
e1	4.95	5.15	0.195	0.203		
F	0.51	0.60	0.020	0.024		
H1	6.20	6.60	0.244	0.260		
J1	2.40	2.72	0.094	0.107		
L	13.00	14.00	0.512	0.551		
L1	3.50	3.93	0.138	0.155		
L20	16.40 typ.		0.646 typ.			
L30	28.90 typ.		1.13	8 typ.		
θР	3.75	3.85	0.148	0.152		
Q	2.65	2.95	0.104	0.116		

DS11576 - Rev 2 page 7/14



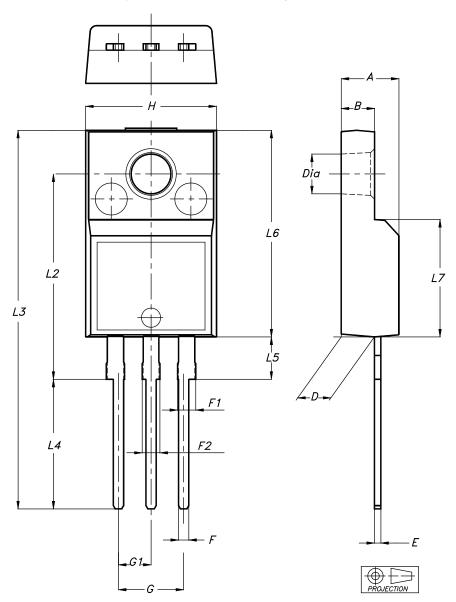
#### 2.2 TO-220FPAB package information

Epoxy meets UL 94,V0

Cooling method: by conduction (C)
Recommended torque value: 0.55 N·m

Maximum torque value: 0.70 N·m

Figure 10. TO-220FPAB package outline



DS11576 - Rev 2 page 8/14



Table 5. TO-220FPAB package mechanical data

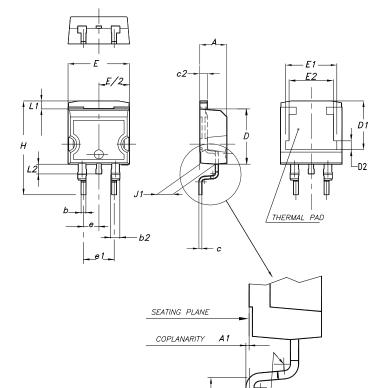
	Dimensions					
Ref.	Millin	neters	Inches (for reference only)			
	Min.	Max.	Min.	Max.		
А	4.40	4.60	0.1739	0.1818		
В	2.50	2.70	0.0988	0.1067		
D	2.50	2.75	0.0988	0.1087		
Е	0.45	0.70	0.0178	0.0277		
F	0.75	1.00	0.0296	0.0395		
F1	1.15	1.70	0.0455	0.0672		
F2	1.15	1.70	0.0455	0.0672		
G	4.95	5.20	0.1957	0.2055		
G1	2.40	2.70	0.0949	0.1067		
Н	10.00	10.40	0.3953	0.4111		
L2	16.0	0 typ.	0.6324 typ.			
L3	28.60	30.60	1.1304	1.2095		
L4	9.80	10.60	0.3874	0.4190		
L5	2.90	3.60	0.1146	0.1423		
L6	15.90	16.40	0.6285	0.6482		
L7	9.00	9.30	0.3557	0.3676		
Dia	3.00	3.20	0.1186	0.1265		

DS11576 - Rev 2 page 9/14



#### 2.3 D<sup>2</sup>PAK package information

- Epoxy meets UL94, V0.
- Cooling method: by conduction (C)



0.25

V2\_

GAUGE PLANE

Figure 11. D<sup>2</sup>PAK package outline

Note: This package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.

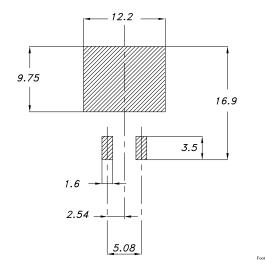
DS11576 - Rev 2 page 10/14



Table 6. D<sup>2</sup>PAK package mechanical data

		Dimensions						
Ref.		Millimeters			Inches (for reference only)			
	Min.	Тур.	Max.	Min.	Тур.	Max.		
А	4.40		4.60	0.173		0.181		
A1	0.03		0.23	0.001		0.009		
b	0.70		0.93	0.028		0.037		
b2	1.14		1.70	0.045		0.067		
С	0.45		0.60	0.018		0.024		
c2	1.23		1.36	0.048		0.053		
D	8.95		9.35	0.352		0.368		
D1	7.50	7.75	8.00	0.295	0.305	0.315		
D2	1.10	1.30	1.50	0.043	0.051	0.060		
E	10.00		10.40	0.394		0.409		
E1	8.30	8.50	8.70	0.335	0.343	0.346		
E2	6.85	7.05	7.25	0.266	0.278	0.282		
е		2.54			0.100			
e1	4.88		5.28	0.190		0.205		
Н	15.00		15.85	0.591		0.624		
J1	2.49		2.69	0.097		0.106		
L	2.29		2.79	0.090		0.110		
L1	1.27		1.40	0.049		0.055		
L2	1.30		1.75	0.050		0.069		
R		0.40			0.015			
V2	0°		8°	0°		8°		

Figure 12. D<sup>2</sup>PAK recommended footprint (dimensions are in mm)



DS11576 - Rev 2 page 11/14



# 3 Ordering information

**Table 7. Ordering information** 

Order code	Marking	Package	Weight	Base qty.	Delivery mode
FERD40H100STS	FD40H100STS	TO-220AB	1.38 g	50	Tube
FERD40H100SG-TR	FD40H100SG	D²PAK	1.48 g	1000	Tape and reel
FERD40H100SFP	FD40H100SFP	TO-220FPAB	1.90 g	50	Tube

DS11576 - Rev 2 page 12/14



# **Revision history**

**Table 8. Document revision history** 

Date	Version	Changes
08-Apr-2016	1	Initial release.
06-Mar-2019	2	Added TO-220FPAB data information.

DS11576 - Rev 2 page 13/14



#### **IMPORTANT NOTICE - PLEASE READ CAREFULLY**

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2019 STMicroelectronics - All rights reserved

DS11576 - Rev 2 page 14/14